

# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
то:	Please return this copy as a certification of your approval
Part No.:	Checked & Approved by:
Customer's Part No.:	Date:

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Part No.	:	R315
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#### **SAW Resonator**

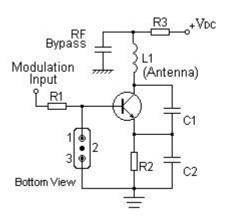
#### **Features**

- 1-port Resonator
- Metal Case for **D11**
- Package size 8.36x3.45x1.70 mm³
- RoHS compatible
- Electrostatic Sensitive Device(ESD)



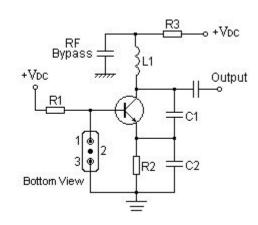
### **Application**

Typical Low-Power Transmitter Application

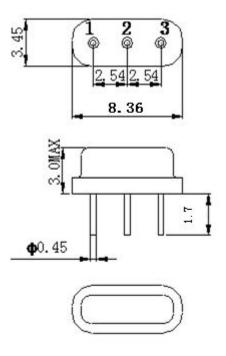


#### Typical Local Oscillator Application

R315



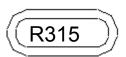
#### Package Dimensions (D11)



#### **Pin Configuration**

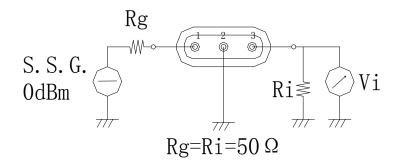
1	Input/output
3	Output/Input
2	Ground

#### Marking

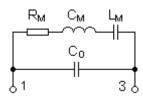


R	SAW Resonator
315	Part number

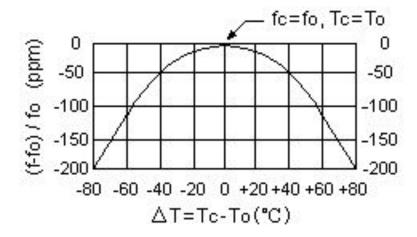
#### **Test Circuit**



#### **Equivalent LC Model**



#### **Temperature Characteristics**



The curve shown above accounts for resonator contribution only and does not include LC component temperature contributions.

#### **Performance**

# **Maximum Rating**

ltem		Value	Unit
DC Voltage	V <sub>DC</sub>	± 30	V
Operation Temperature	Т	-40 ~ +85	$^{\circ}$
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	${\mathbb C}$
RF Power Dissipation	Р	10	dBm

#### **Electronic Characteristics**

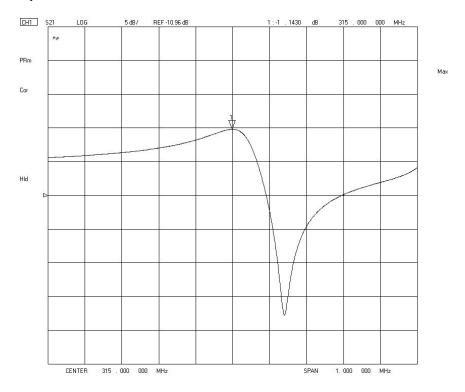
Test Temperature:  $25^{\circ}C \pm 2^{\circ}C$ 

Terminating source impedance:  $50\Omega$  Terminating load impedance:  $50\Omega$ 

	Itém		Minimum	Typical	Maximum	Ųnit
Center	Absolute Frequency	fc		315.00		MHz
Frequency	Tolerance from 315.00MHz	△fc		± 75		KHz
Insertion Loss(r	ertion Loss(min) IL 1.2 1.3		1.8	dB		
Ovality Faster	Unloaded Q	Qυ		16060		
Quality Factor	50Ω Loaded Q	QL		1844		
Temperature Stability	Turnover Temperature	T <sub>0</sub>	10	25	40	$^{\circ}$
	Turnover Frequency	f <sub>0</sub>		f <sub>c</sub>		KHz
-	Frequency Temperature Coefficient	FTC		0.032		ppm/℃
Frequency Aging				≤ 10		ppm/yr
DC Insulation R	esistance between Any Two Pins		1.0			$M\Omega$
	Motional Resistance	R <sub>M</sub>		13	22	Ω
RF Equivalent	Motional Inductance	L <sub>M</sub>		105.3		μН
RLC Model	Motional Capacitance	См		2.43		fF
	Static Capacitance	C <sub>0</sub>	2.8	3.1	3.4	pF

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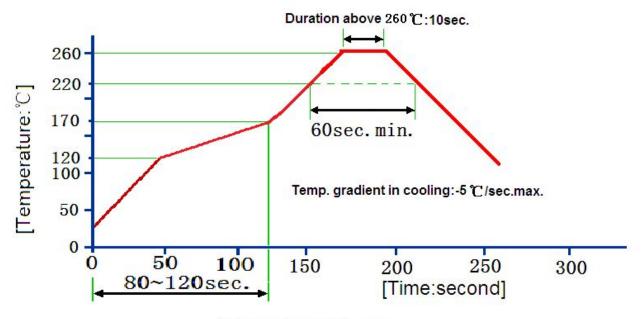
# **Frequency Response**



# Reliability (The SAW components shall remain electrical performance after tests)

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: −40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60℃±2℃,90~95% RH
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min , Cycle time: 100 times , Recovery time : 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm  Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: 245°C±5°C Duration: 3.0s5.0s Depth: DIP2/3 , SMD1/5
7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: 260 ℃ ±5 ℃ , Duration: 10±1s (2)Temperature of Soldering Iron: 350 ℃ ±10 ℃ , Duration: 3~4s , Recovery time : 2 ± 0.5h

## **Recommended Reflow Soldering Diagram**



#### Reflow cycles:3 cycles max.

#### **Notes**

- 1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
- 2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.